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APPROVAL SHEET

Customer:					
Part Number:					
Part No.:	11414020000.0015				
Holder:	OCXO-14				
Frequency:	20MHz				
Manufacturer:					
Date:	2023-03-22				

Prepared	Checked	Approved

(For Customer Use)

Acceptable	Non-Acceptable

Revision History

No.	Revised Date	Change Content	Approved	Remark
1.0	2023-3-22	Initial Release		

1. Scope

This document describes technical guidelines of product 11414020000.0015

2. Electrical Characteristics

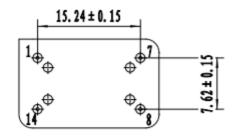
		HCMOS OUTPUT O	CXO-14			
PARAMETER	PARAMETER SYMBO CONDITIONS MIN TYPE MAX					
Normal Fn			20		MHz	
Absolute maxin	num ratings	5				
Maximum Supply Range	Vcc	-	-0.3		+5.5	V
Operating Temperature range	TA	-	-40		85	°C
Storage Temperature range			-55		125	°C
Power						
Operating Supply Voltage	V _{cc}		4.75	5	5.25	V
Turn-On Current		Nom Vcc			2.5	W
Steady state Current		Ta=25°C			1	W
Frequency Stab	oility			•		
Calibration		T _A =25℃			±0.5	ppm
Freq VS Temperature	Ts	-40°C to 85°C			±20	ppb
Freq VS Time (Aging)		1st year			±1.5	ppm
. 3 0,		10 years			±4	ppm
Warm up time		time to ±0.5 of F _n			3	minutes
Output paramet	ers		·			
Output signal		-		HCMOS		
Output load		Output to ground	13.5	15	16.5	pF

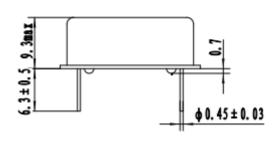
Outset Lavel	V _{OH}	High Level	4.5			V
Output Level	V _{OL}	Low Level			0.5	V
Duty Cycle			45	50	55	%
Rise time/ Fall					6	no
time					0	ns
		10Hz		-110		dBc/Hz
		100Hz		-130		dBc/Hz
Phase noise		1KHz		-140		dBc/Hz
		10KHz		-148		dBc/Hz

		100Hz			-130		dBc/Hz	
Phase noise			1KHz		-140		dBc/Hz	
			10KHz		-148		dBc/Hz	
3. Construction	3. Construction							
Oscillator enclosure seal:								
□Seam se	eal ■ resi	istance weld	□ cold weld					
2. crystal enclosu	ure medium							
□nitrogen	■vac	uum	□dry air					

4.Dimension:





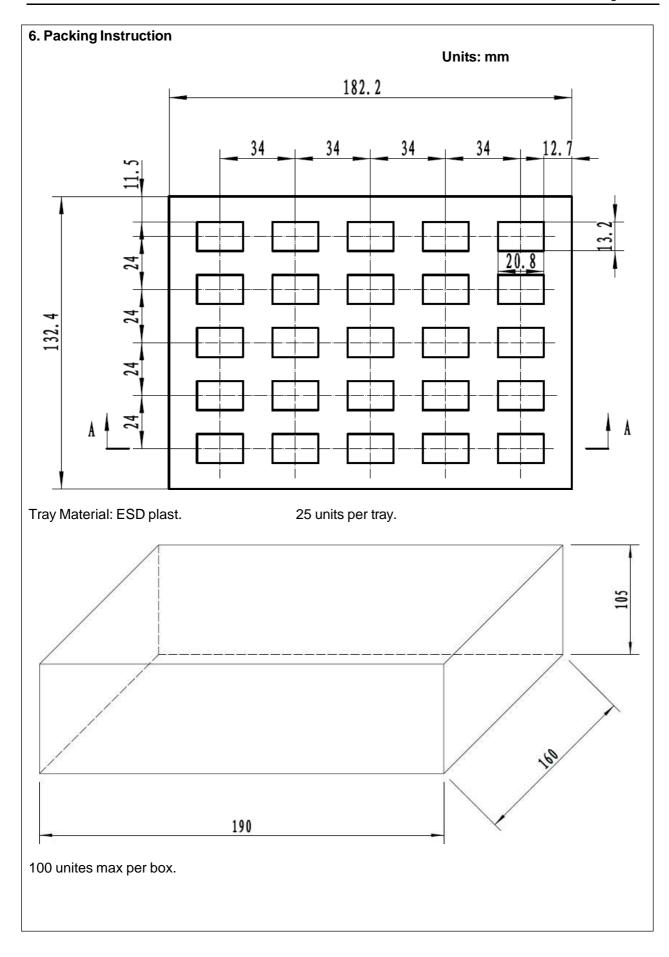


PIN/PAD	FUNCTION:		
1	Control Voltage/NC		
7	GND		
8	Output		
14	Power Supply		

5. Marking

■ Laser Marking

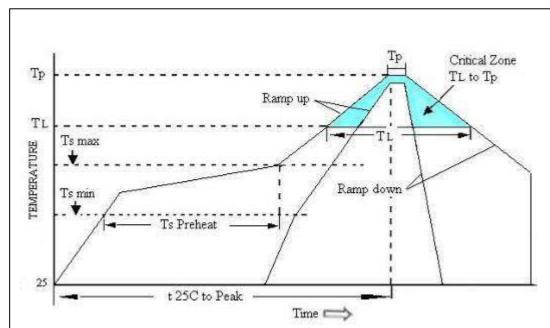
☐ Ink Marking



.Rel	iability charact	eristic:	
	Item	Condition	Specifications
7. 1	Reflow	3X 240°C Peak	ΔF≤±0.2ppm
	Simulation	20 secs max above 240°C	
7. 2	Power Cycl	100 Cycles	ΔF≤±0.2ppm
		-40°C, 30 minutes no power (off) and 30 minutes	
		powered (on)	
		Test product for functionality	
		Continue for another 250 cycles	
		Test product for functionality	
		Intenal visual and mechanical inspection	
7.3	Thermal Shock	Subject samples to temperature extremes of -40 and	ΔF≤±0.2ppm
		+125C, 30 minute soaks at the temperature extremes,	
		10 seconds maximum transition time between	
		extremes. The test duration is 10 Cycles	
		GJB 360A-96 Method 107.	
7.4	Mechanical	IEC 68-2-27 Test Ea	ΔF≤±0.2ppm
	Shock		
7.5	Vibration	IEC 68-2-06 Test Fc	ΔF≤±0.2ppm
7.6	Free drop	Drop from 10cm height on 3cm hard wooden board for 6	ΔF≤±0.2ppm
		Aire an	
		times	
		GB2423.8-1995 (idt IEC 68-2-32:1990) Method Ed。	
7. 7	Aging	Bias oscillators at nominal voltage and subject	Per. Spec.
		oscillators to 25C for 1008 hours. Readings are to be	
		taken with oscillator at 25C twice per day. Determine	
		aging (frequency shift post 1008 hours minus initial	
		frequency). Use the results to predict long-term aging.	
7.8	Solderability	Precondition parts by steaming (over boiling water) for 8	A new uniform coating of
		D 4 14500 (10)	solder shall cover a minimum
		hours OR age the parts at 150C for 16 hours	of 95% of the surface being
			immersed.

8.All products are RoHs compliant

9. Reflow Profile



High Temperature Infrared /Convection

Note:Temperature shown are applied to body of device

Ts max to T _L (Ramp-up Rate)	3℃/second max	
Preheat		
Temperature Min(Ts Min)	150℃	
Temperature Typical(Ts Typ)	175℃	
Temperature Max.(Ts Max)	200℃	
Time(ts)	60-180 seconds	
Ram-up Rate(T _L to Tp)	3°C/second Max	
Time Maintained Above:		
Temperature(T _L)	217℃	
Time(T _L)	60-150seconds	
Peak Temperature (Tp)	260°C Max for 10 seconds	
Time within 5℃ of actual peak(t _p)	20-40 seconds	
Ramp-down Rate	6°C/seconds Max	
Tune 25°C to Peak Temperature(t)	8 minutes Max	
Moisture Sensitivity Level	Level 1	

High Temperature Manual Soldering

Note:Temperature shown are applied to body of device